# R163-P30-AAG1

# Rack Server - 1U UP 4-Bay NVMe/SATA







## **Features**

- Single AmpereOne® Family Processors
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture
- 1 x 1Gb/s LAN port via Intel<sup>®</sup> I210-AT
- 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCle Gen5 x4 interface
- 2 x FHHL PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- 2 x 800W 80 PLUS Titanium redundant power supply

# **Application**

Networking, Hybrid/Private Cloud Server...

## **Specification**

Dimensions	1U (W438 x H43.5 x D710 mm)	I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x RJ45, 1 x Mini-DP, 1 x MLAN
Motherboard	MP33-DC0		, , ,
СРИ	AmpereOne® Family Processors Up to 192 custom cores Single processor, TDP up to 400W	Backplane Board	Speed and bandwidth: PCle Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
		Security Modules	1 x TPM header with SPI interface - Optional TPM2.0 kit: CTM010
Sock	1 x LGA 5964		·
Chipset	System on Chip	Power Supply	2 x 800W 80 PLUS Titanium redundant power supply AC Input: 100-240V
Memory	16 x DIMM slots 8-Channel DDR5 memory architecture RDIMM: Up to 5200 MT/s, 4400 MT/s (2R 2DPC)	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
	TIBININI. OF IC CECC INTIO, THOU INTIO (ETTEBT C)	System Fans	2 x 40x40x28mm (25,000rpm)
LAN	1 x 1Gb/s LAN port (Intel® I210-AT) - Supports NCSI function 1 x 10/100/1000 Mbps management LAN		4 x 40x40x56mm (32,000rpm)
		Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8%-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Video	Integrated in ASPEED® AST2600 - 1 x Mini-DP		
Storage	Front hot-swap: 4 x 3.5"/2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays* *SAS card is required to support SAS drives. Internal M.2: 1 x M.2 (2280/22110), PCIe Gen5 x4		Non-operating numbers, 20 /0-93 /6 (non-condensing)
		Packaging Content	1 x R163-P30-AAG1, 1 x CPU heatsink, 1 x Carrier, 1 x Mini-DP to D-Sub cable, 1 x 2-Section Rail kit
			Packaging Dimensions: 977 x 588 x 236 mm
		Part Numbers	Barebone package: 6NR163P30DR000ABG1* Optional parts: - 3-Section Rail kit (Supports CMA): 25HB2-A56120-K0R - Cable Management Arm: 25HBZ-R18100-K0R
RAID	Require RAID add-in cards		
Expansion Slots	2 x FHHL PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots		



#### Learn more at https://www.GIGABYTE.com/enterprise

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